Hits	Search Text	DB	Time stamp
2408	<pre>pad and area and (solder adj ball) and substrate</pre>	USPAT; US-PGPUB;	2003/05/28 10:56
24	(die adj pad) and PCB and wiring	DERWENT; IBM_TDB USPAT;	2002/03/07
17	(("5280192") or ("5579207") or	EPO; JPO; DERWENT; IBM_TDB	2002/03/07
1,	("6072233") or ("6180881") or ("5872025") or ("6093029") or ("5963430") or ("6313522")).PN.	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	14:54
0	(metal adj peg) and (printed adj circuit adj line)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/03/07
111	metal adj peg	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/03/07 14:56
1	(metal adj peg) and packaging	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/03/07 14:57
7	(metal adj peg) and (die chip)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/03/07 15:39
210	257/697.ccls. and wiring	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/03/07 17:09
4317	(chip die) and wiring and ball	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/03/07 17:10
46	((chip die) and wiring and ball) and (circuit adj line)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/03/08
. 9	(("6201292") or ("6247229") or ("6025640") or ("6281047")).PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/03/08 17:08
4	(("6069396") or ("6232636")).PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/03/08
8	(("6229205") or ("6204090") or ("5965947") or ("6157074")).PN.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/03/08 13:44
	2408 24 17 0 111 1 7 210 4317 46	2408 pad and area and (solder adj ball) and substrate 24 (die adj pad) and PCB and wiring 17 (("5280192") or ("5579207") or ("6072233") or ("6180881") or ("5872025") or ("6093029") or ("5963430") or ("6313522")).PN. 0 (metal adj peg) and (printed adj circuit adj line) 111 metal adj peg) and packaging 7 (metal adj peg) and (die chip) 210 257/697.ccls. and wiring 4317 (chip die) and wiring and ball 46 ((chip die) and wiring and ball 46 ((chip die) and wiring and ball) and (circuit adj line) 9 (("6201292") or ("6247229") or ("6025640") or ("6281047")).PN. 4 (("6069396") or ("6232636")).PN.	2408 pad and area and (solder adj ball) and substrate USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J

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	970	line adj mask	USPAT;	2002/03/08
-	970	Tine adj mask	US-PGPUB;	13:45
			EPO; JPO;	13.10
			DERWENT;	
			IBM TDB	•
-	0	(line adj mask) and (insulating adj	USPĀT;	2002/03/08
		paint)	US-PGPUB;	13:45
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	0000/00/00
-	0	(line adj mask) and paint and trace	USPAT;	2002/03/08 13:46
			US-PGPUB; EPO; JPO;	13:46
			DERWENT;	
			IBM TDB	
_	455	(line adj mask) and circuit	USPAT;	2002/03/08
		,,	US-PGPUB;	13:46
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	10	, ,	USPĀT;	2002/03/11
1	1	adj printing)	US-PGPUB;	10:29
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB USPAT;	2002/02/09
-	22	mask near5 paint and thermally	USPAT; US-PGPUB;	2002/03/08 17:09
]		EPO; JPO;	11.09
			DERWENT;	
			IBM TDB	
_	974	257/718-720.ccls. and (heat adj sink)	USPAT;	2002/03/11
		10 · , · 10 · , 10 · 00 10 ·	US-PGPUB;	10:34
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3		USPAT;	2002/03/11
		(die adj pad)	US-PGPUB;	10:33
			EPO; JPO; DERWENT;	
ļ			IBM TDB	
_	41	(257/718-720.ccls. and (heat adj sink))	USPAT;	2002/03/11
	Ţ.	and encapsulant	US-PGPUB;	10:40
	į l		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	("5291062").PN.	USPĀT;	2002/03/11
			US-PGPUB;	10:48
İ			EPO; JPO;	
			DERWENT;	
	300	(hand add mad) and (hank add adal)	IBM_TDB USPAT;	2002/02/11
-	329	(bond adj pad) and (heat adj sink)	USPAT; US-PGPUB;	2002/03/11
			EPO; JPO;	10.49
			DERWENT;	
			IBM TDB	
-	189	(bond adj pad) and (heat adj sink) and	USPAT;	2002/03/11
		257/\$	US-PGPUB;	10:50
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/02/22
-	78	257/697,711,737-738,666.ccls. and (wiring	USPAT;	2002/08/20
		adj connect\$4)	US-PGPUB; EPO; JPO;	16:13
			DERWENT;	ļ
]		IBM TDB	
_	70	438/15,106,112,121,124,612.ccls. and	USPAT;	2002/08/20
	'3	(metal adj substrate)	US-PGPUB;	16:38
		,	EPO; JPO;	
	ļ		DERWENT;	
			IBM_TDB	